

SEMITOP[®] 3

3-phase bridge rectifier + brake chopper +3-phase bridge inverter SK 10 DGDL 065 ET

Preliminary Data

Features

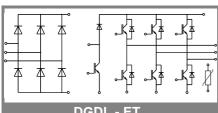
- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded alumium oxide ceramic (DCB)
- Ultrafast NPT technology IGBT
- CAL Technology FWD
- Integrated NTC temperature sensor

Typical Applications*

Inverter

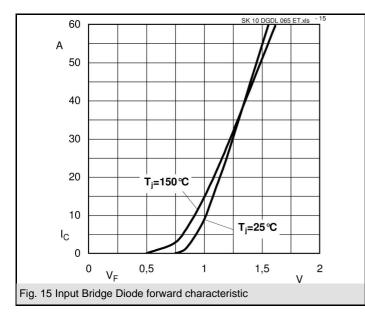
| Absolute Maximum Ratings | | T_s = 25°C, unless otherwise specified | | | | | |
|-------------------------------------|--|--|-------|--|--|--|--|
| Symbol | Conditions | Values | Units | | | | |
| IGBT - Inverter, Chopper | | | | | | | |
| V _{CES} | | 600 | V | | | | |
| Ι _C | T _s = 25 (80) °C | 17 (11) | А | | | | |
| I _{CRM} | $I_{CRM} = 2 \times I_{Cnom}, t_p = 1 \text{ ms}$ | 20 | А | | | | |
| V _{GES} | | ±20 | V | | | | |
| Т _ј | | -40 +150 | °C | | | | |
| Diode - Inverter, Chopper | | | | | | | |
| I _F | T _s = 25 (80) °C | 22 (15) | А | | | | |
| I _{FRM} | $I_{FRM} = 2xI_{Fnom}, t_p = 1 \text{ ms}$ | 28 | А | | | | |
| T _j | | -40 +150 | °C | | | | |
| Rectifier | | | | | | | |
| V _{RRM} | | 800 | V | | | | |
| I _F | T _s = 80 °C | 21 | А | | | | |
| I _{FSM} / I _{TSM} | t _p = 10 ms , sin 180 ° ,T _j = 25 °C | 220 | А | | | | |
| I ² t | t _p = 10 ms , sin 180 ° ,T _j = 25 °C | 240 | A²s | | | | |
| Т _ј | | -40 +150 | °C | | | | |
| T _{sol} | Terminals, 10s | 260 | °C | | | | |
| T _{stg} | | -40 +125 | °C | | | | |
| V _{isol} | AC, 1 min. / 1s | 2500 / 3000 | V | | | | |

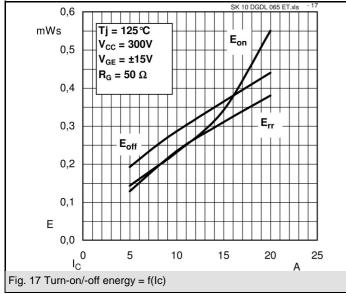
| Characteristics | | T _s = 25°C | T_s = 25°C, unless otherwise specified | | | | | |
|--------------------------|--|-----------------------|--|------|-------|--|--|--|
| Symbol | Conditions | min. | typ. | max. | Units | | | |
| IGBT - Inverter, Chopper | | | | | | | | |
| V _{CEsat} | I _C = 6 A, T _j = 25 (125) °C | | 2 (2,3) | 2,5 | V | | | |
| V _{GE(th)} | $V_{GE} = V_{CE}, I_{C} = 0,5 \text{ mA}$ | 3 | 4 | 5 | V | | | |
| V _{CE(TO)} | T _j = 25 °C (125) °C | | 1,2 (1,1) | 1,3 | V | | | |
| r _T | T _j = 25 °C (125) °C | | 133 (183) | 200 | mΩ | | | |
| Cies | V_{CE} = 25 V_{GE} = 0 V, f = 1 MHz | | 0,5 | | nF | | | |
| C _{oes} | $V_{CE} = 25 V_{GE} = 0 V, f = 1 MHz$ | | 0,1 | | nF | | | |
| C _{res} | $V_{CE} = 25 V_{GE} = 0 V, f = 1 MHz$ | | 0,1 | | nF | | | |
| $R_{th(j-s)}$ | per IGBT | | | 2 | K/W | | | |
| t _{d(on)} | under following conditions | | 45 | | ns | | | |
| t _r | V_{CC} = 300 V, V_{GE} = ± 15 V | | 30 | | ns | | | |
| t _{d(off)} | I _C = 6 A, T _j = 125 °C | | 340 | | ns | | | |
| t _f | $R_{Gon} = R_{Goff} = 210 \ \Omega$ | | 25 | | ns | | | |
| E _{on} | inductive load | | 0,18 | | mJ | | | |
| E _{off} | | | 0,13 | | mJ | | | |
| Diode - Ir | verter, Chopper | | | | | | | |
| $V_F = V_{EC}$ | I _F = 6 A, T _i = 25(125) °C | | 1,3 (1,2) | 1,5 | V | | | |
| V _(TO) | T _j = 25 °C (125) °C | | 1 (0,9) | 1,1 | V | | | |
| r _T | T _j = 25 °C (125) °C | | 45 (50) | 60 | mΩ | | | |
| R _{th(j-s)} | per diode | | | 2,3 | K/W | | | |
| I _{RRM} | under following conditions | | 8,4 | | А | | | |
| Q _{rr} | I _F = 6 A, V _R = 300 V | | 0,8 | | μC | | | |
| Err | V _{GE} = 0 V, T _j = 125 °C | | 0,18 | | mJ | | | |
| | di _{F/dt} = 170 A/µs | | | | | | | |
| Diode red | tifier | | | | | | | |
| V _F | I _F = 15 A, T _i = 25() °C | | 1,1 | | V | | | |
| V _(TO) | T _i = 150 °C | | 0,8 | | V | | | |
| r _T | T _i = 150 °C | | 20 | | mΩ | | | |
| R _{th(j-s)} | per diode | | | 2,7 | K/W | | | |
| Temperatur sensor | | | | | | | | |
| R _{ts} | 5 %, T _r = 25 (100) °C | | 5000(493) | | Ω | | | |
| Mechanical data | | | | | | | | |
| w | | | 30 | | g | | | |
| M _s | Mounting torque | | | 2,5 | Nm | | | |
| | • | | | | | | | |

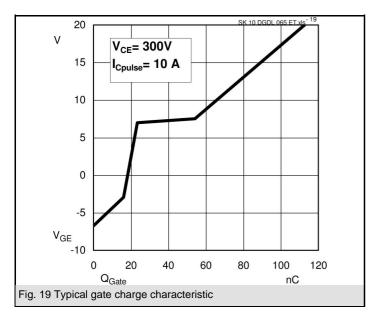


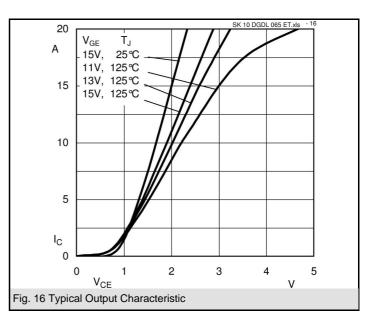
DGDL - ET

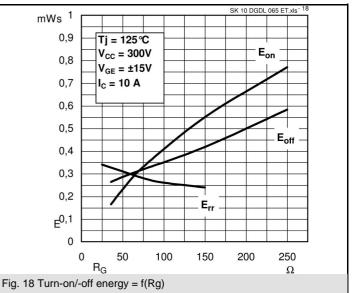
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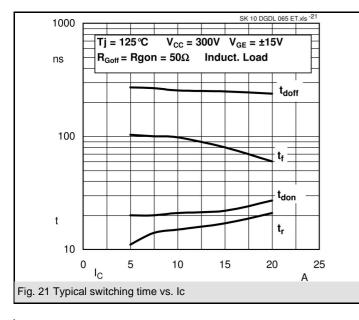


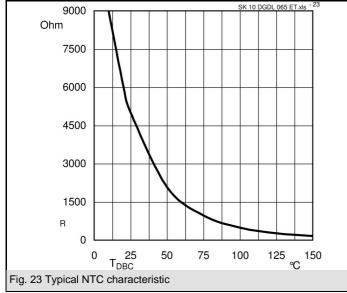


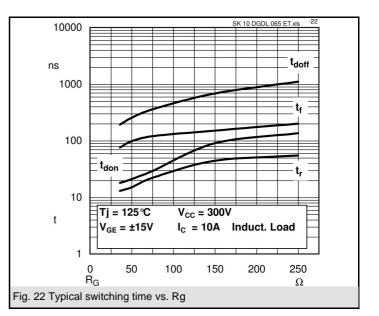


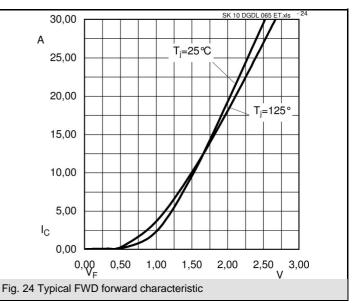


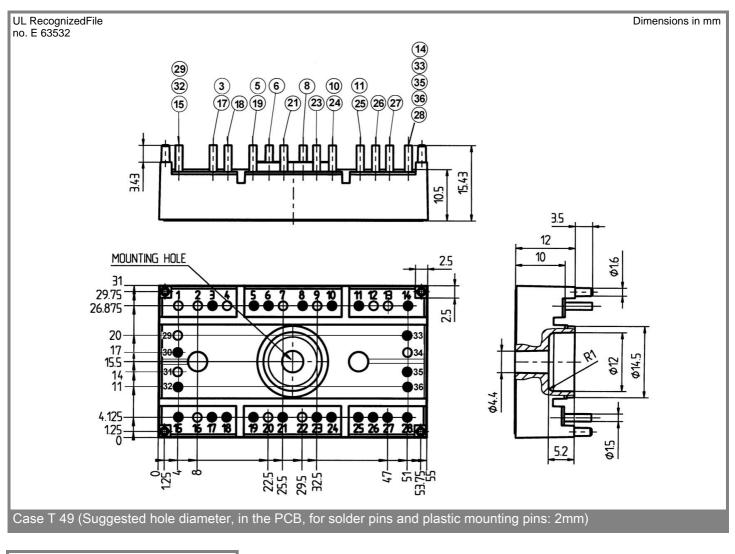


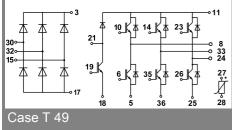












This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.